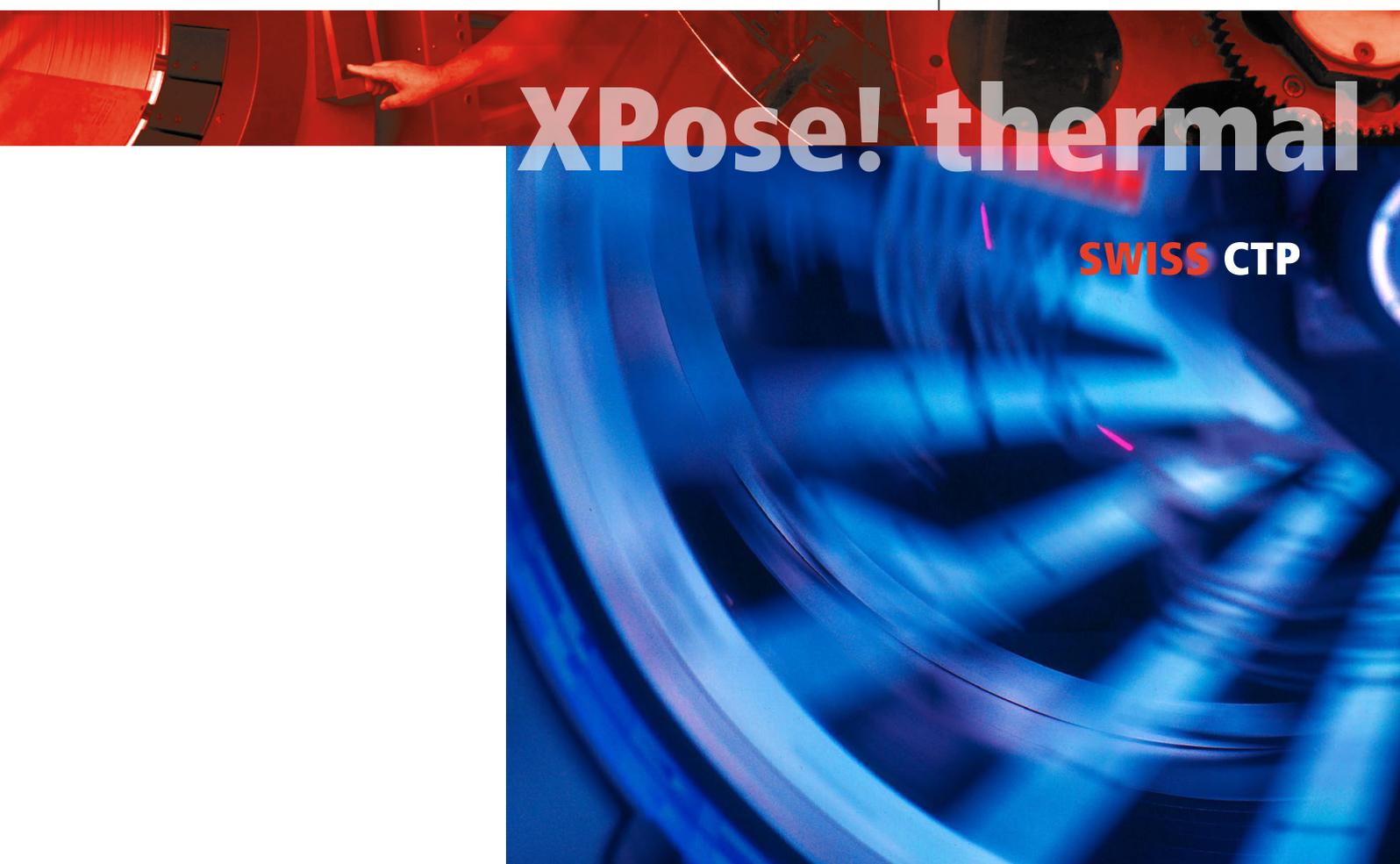


XPose! thermal
Digital platesetters for
thermal offset plates



XPose! thermal

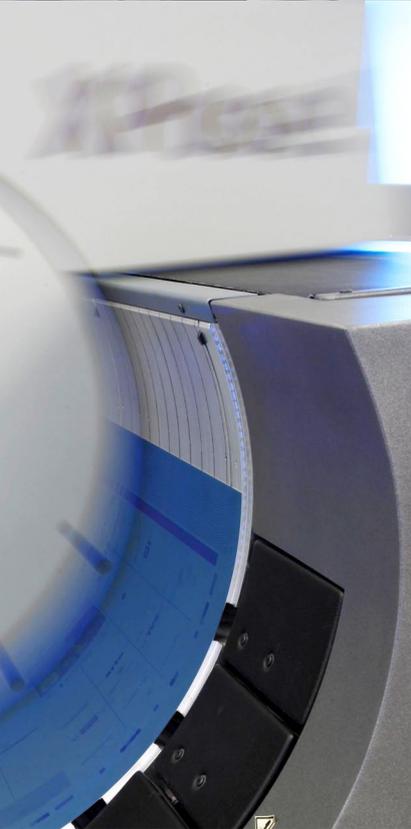
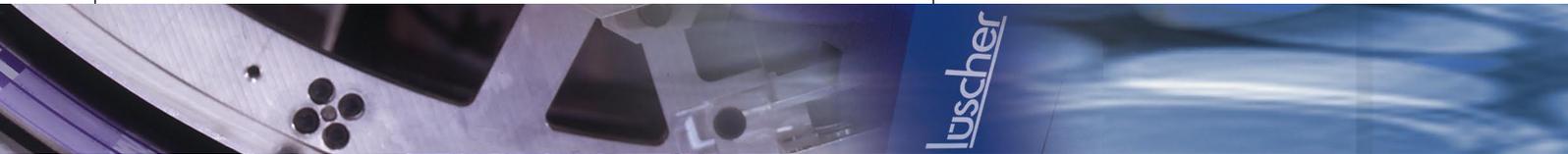
SWISS CTP

luscher

SWISS CTP from Lüscher

- More than 60 years experience in prepress
- XPose! revolutionary modular system design
- Use of proven plate technology offering numerous advantages
- Quality and reliability that our customers are delighted with
- Simple, user-friendly operation

XPose! thermal sets thermal plates worldwide with over 1,000 satisfied customers



XPose! thermal Computer-to-Plate technology ensures the highest quality all the way from the original data set to the printing plate.

In the design of the XPose! thermal Lüscher has incorporated both the wishes of customers and the results of continuous research and development in order to maximize user and service friendliness in particular. And all of course achieved whilst maintaining unbeatable system availability.

The design of the new XPose! thermal generation incorporates new mechanics and an improved optical and laser system. Besides the new setting head, numerous improvements have been made to the electrical systems and the software to enable you to enjoy the full benefit of advances in technology.

The high-powered laser diodes, which are constantly monitored and automatically adjusted as necessary, offer reliable production. Should a diode actually fail, the XPose! thermal will continue to operate without any loss of quality, although somewhat more slowly.

In response to the increasing market presence of large format presses, Lüscher supplies models up to the XL plate format of 2260 x 1600 mm. XPose! thermal VLF platesetters also offer performance features and properties that are of crucial importance to large format printers.

Lüscher platesetters can be operated manually or, as an option, semi- or fully automatically.

XPose! has a flexible modular design. Its consequent optimization is the key to demonstrably low operating and service costs.

**XPose! thermal model range up to
2260 x 1600 mm XL plate format**



XPose! 230 thermal



XPose! 260 thermal



XPose! 290 thermal



XPose! 290-L thermal



XPose! 290-XL thermal

The new XPose! thermal model range incorporates the latest technology for maximum service availability and minimum servicing expenditure.

The XPose! thermal model range can cover all the required formats from 430 x 360 mm to 2260 x 1600 mm, the XL plate format.

The new XPose! Thermal is based on the XPose! technology that has been used with such success around the world and which combines speed with consistency. Its unique combination of internal and external drum is patented worldwide. This design guarantees geometrically precise reproduction and simplifies the loading and unloading of the plates.

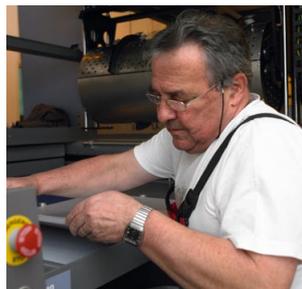
Lüscher platesetters can be used manually or, optionally, as semi- or fully automatic machines.

Professional service and support as well as user friendliness make your life simpler



No waiting! Operational check via remote maintenance.

Product innovations are implemented through close and direct exchanges with our customers and partner companies, because at Lüscher development, manufacture and support are all from the same source. This means that we actively support each XPose! thermal in your company through on site customer aids, preventive maintenance checks and comprehensive operator training and maintenance courses for a customer's own staff. As a result we help you to avoid production down times and to save costs.

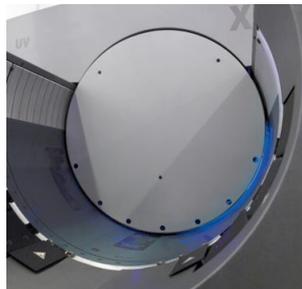


Active support. A service team will arrive on site within the shortest possible time to assist you.

All the important components are easily accessible for servicing.

A special diagnostic tool allows our service engineers to analyse a problem on site in your company, which ensures highly efficient and top quality service.

A Color Touch Panel (graphic user interface), which is simple to operate and a joy to use because of its clear display of individual operational functions, controls the setter. Dynamic menus offer you easy access to the key functions at any time.



Any plate format. The simplified construction of the internal drum reduces the footprint.

Customer satisfaction remains our primary objective and so we value a mutual development partnership very highly and relish the challenge of finding customer specific solutions.

Innovative options that deliver enhanced functionality and operator comfort

Inline punching – taking fully automatic prepress further

To finally make register errors a thing of the past and achieve fully automatic production, the XPose! can be fitted with the integrated Bacher 2000 inline punching system. On request, other, customer specific punches can be integrated. Perfect register allows makeready times to be shortened and waste minimized. – The inline punching system combined with fully automatic operation through the use of the Lüscher Plate Handling System offers the highest possible level of automation for your prepress.



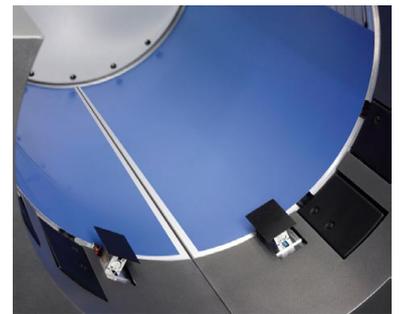
XPose! PHS – Plate Handling-System for fully automatic operation

The XPose! PHS offers efficient plate handling and is specifically recommended for companies dealing with high volumes or for the professional handling of VLF plates. The Plate Handling System can accommodate up to six different formats or thicknesses of plate and the automation reduces the risk of damaging the plates. In addition, the PHS is very simple to load, since the interleaved sheets of paper are automatically removed.



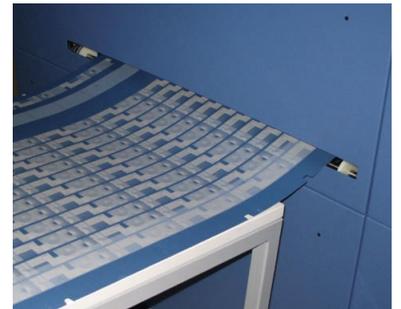
XPose! Dual platesetting – unlimited flexibility

Dual platesetting increases productivity and reduces production costs, since two smaller plates can be exposed together on the plate bed. Dual platesetting therefore offers a combination of first class quality, high throughput and efficient plate handling. The modular architecture of the XPose! Setter means that each Dual model is built to the individual platesetting requirements of the customer.



XPose! unloader for semi-automatic operation

The optional plate deloader automatically unloads the plates after setting and directly forwards them to the plate processing line.



Technical specifications

XPose! 230 thermal XPose! 260 thermal XPose! 290 thermal XPose! 290-L thermal XPose! 290-XL thermal

Max. plate format	1130 x 950 mm	1680 x 1370 mm	1900 x 1485 mm	2080 x 1600 mm	2260 x 1600 mm
Max. exposure area	full plate format				
Min. plate format	430 x 360 mm	540 x 380 mm	605 x 410 mm	655 x 410 mm	655 x 410 mm
Min. plate format with register pins	120 x 120 mm				
Min. exposure area	none	none	none	none	none
Plate thickness with PHS	0.15 - 0.4 mm	0.15 - 0.5 mm			
Resolution	2400 dpi				
Thermal exposure head	64 laser diodes				
Light source	thermal, 830 nm				
Dimensions (L x W x H)	2908 x 1367 x 1627 mm	3626 x 1565 x 1735 mm	4126 x 1794 x 2008 mm	4126 x 1794 x 2008 mm	4126 x 1794 x 2008 mm
Weight	1900 kg	2550 kg	3500 kg	3500 kg	3500 kg
Options					
Downgrade	32 laser diodes				
Upgrade	unavailable	128 laser diodes	128 laser diodes	128 laser diodes	128 laser diodes
Plate Handling System fully automated	available	available	available	available	available
Semi-autom. unloader	available	available	on request	on request	unavailable
Dual XPose!	on request	available	available	available	available
Inline punching	available	available	available	available	available
Further resolutions	on request				

Power supply 3 x 400 V, 50-60 Hz + N+ PE 32 A
 Ambient conditions 50 - 65% ambient humidity at 18 - 25°C

Technical details subject to change

Lüscher